

DOCKET NO: 221608US0PCT



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

:

MINORU TAKAYA, ET AL.

: EXAMINER: JOHNSON, J. J.

SERIAL NO: 10/089,067

:

FILED: APRIL 5, 2002

: GROUP ART UNIT: 1725

FOR: SOLDERING FLUX, SOLDER
PASTE AND METHOD OF SOLDERING

AMENDMENT

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Responsive to the Office Action dated June 3, 2004, Applicants respectfully request reconsideration of the above-identified application in view of the following amendment and remarks.

Amendments to the Specification begins on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Discussion of the Amendment begins on page 19 of this paper.

Remarks begin on page 20 of this paper.

12/01/2004 FMETEK1 00000045 10089067

01 FC:1201
02 FC:1202

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